



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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TG-CJ-Li-12-12-10-PF Ceramic Heat Spreader



Features

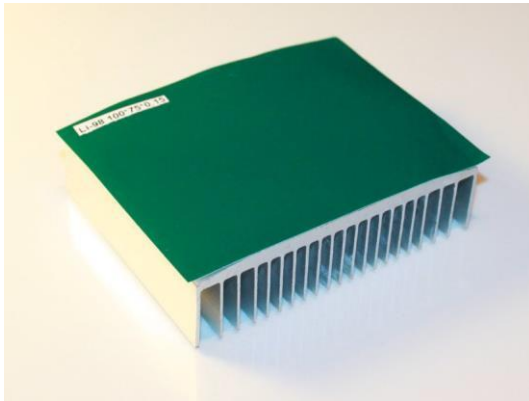
Large contact area
Low weight
High breakdown voltage
Excellent heat spreader
Custom shapes possible

Applications

LED/ NotebookPC/ M/B/ PowerTransistor/ PowerModule/CPU/ ChipIC

Main Component			AL ₂ O ₃
Physical Property	Density	g/cm ³	3.66
	Water Absorption	%	0.002
	Sinter Temperature	°C	1700
	Acid resistance	mg/cm ³	≤ 0.2
	Alkali	mg/cm ³	≤ 0.2
Mechanical Property	Mohs Hardness	HV	9
	Bend Strength	Mpa	≥ 610
	Compression Intensity	Mpa	≥ 620
Thermal Property	Maximum working temperature	°C	1400
	Refractoriness	°C	≥ 1500
	thermal expansion coefficient	(1 x 10 ⁻⁶)mm/°C	7.8 ~ 8.3
	Thermal Shock resistance	T(°C)	200
	Thermal Conductivity	W/m.k	40 ~ 51
Electrical Property	Resisting rate of Volume	Ω. °C	1016
	DC breakdown strength	KV/mm	15.2 ~ 16.7
	Insulation Breakdown Intensity	KV/mm	18
	Dielectric Constant (1MHz)	(E)	10
	Dielectric Dissipation	(tg o)	0.4*10 ⁻³

Li-98 ThermalTape



Features

- Good adhesion
- Very good thermal conductivity
- Highly compressible
- Easy to assemble

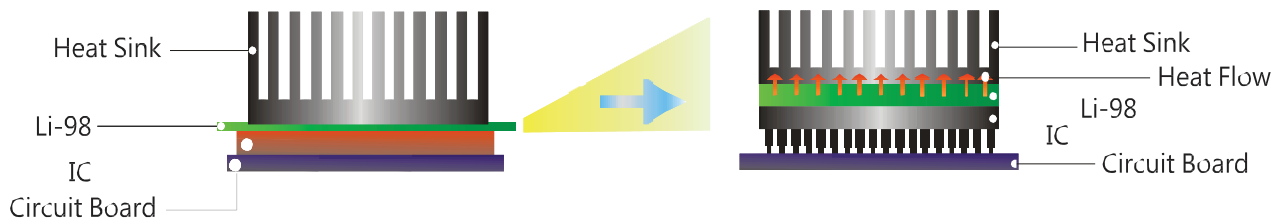
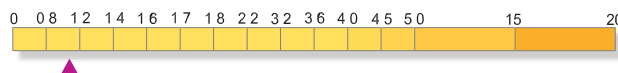
Applications

- Electronic components: IC/CPU/MOS
- LED/M/B/P/S/Heat Sink/LCD-TV/Notebook PC/PC/Telecom Device/Wireless Hub etc...
- DDR II Module/ DVD Applications/ Hand-Set applications etc...

Properties

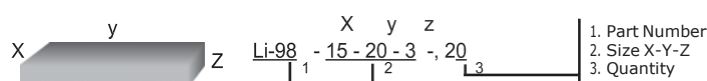
- REACH Compliant
- RoHS Compliant

Thermal Conductivity: 0.95 W/mK
(W/mK - Z Axis)



Property	Li-98	Li-98C	Li98CN	Unit	Test Method
Thickness	0.15	0.25	0.2	0.18	ASTM D374
Colour	White	White	White	White	Visual
Reinforcement Carrier	Fibreglass mesh				
Density	1.85	1.85	1.9	1.8	g/cm ³ ASTM D792
Tensile Strength	200	400	200	50	psi ASTM D412
Glass Transition Temperature	-30	-30	-27	-30	°C
Short Time Use Temperature (30sec)	200	200	200	200	°C
Continuous Working Temperature	-30 to 120	-30 to 120	-30 to 120	-30 to 120	°C
Thermal Conductivity	0.95	0.95	1.8	2	W/mK ASTM D5470
Thermal Impedance @ <1psi	1.0	1.8	0.7	0.6	Cin 2/W ASTM D5470
Thermal Impedance @ 50psi	0.9	1.5	0.5	0.3	Cin 2/W ASTM D5470
Initial Tack	11	10	14	15	cm PSTC-6
Lap Shear Strength	61	61	65	55	N/cm ² ASTM D1002
Die Shear Strength @ 25 °C	120	120	118	100	N/cm ² -
Die Shear Strength @ 80 °C	69	69	68	55	N/cm ² -
Holding Power 1000g @ 25 °C using 1 in ²	>10000	>10000	>10000	>10000	min PSTC-7
Holding Power 1000g @ 80 °C using 1 in ²	>10000	>10000	>10000	>10000	min PSTC-7
180° Peeling Strength (aluminium)	4	5	4	3	N/cm ASTM D3330
Dielectric Breakdown Voltage (Vac)	>2	>3	>3	>5	kV ASTM D149
Dielectric Breakdown Voltage (Vdc)	>3	>4	>4	>6	kV ASTM D149

Available with an adhesive backing



- Part Number
- Size X-Y-Z
- Quantity